DECEMBER 1983-REVISED MARCH 1988

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

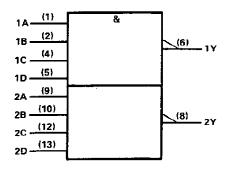
These devices contain two independent 4-input NAND gates.

The SN5420, SN54LS20, and SN54S20 are characterized for operation over the full military range of $-55\,^{\circ}\text{C}$ to 125 $^{\circ}\text{C}$. The SN7420, SN74LS20, and SN74S20 are characterized for operation from 0 $^{\circ}\text{C}$ to 70 $^{\circ}\text{C}$.

FUNCTION TABLE (each gate)

	INP	UTS		QUTPUT
Α	В	С	D	Y
н	Н	Н	н	Ļ
L	х	Х	х	Н
x	L	X	x	Н
х	Х	L.	×	н
х	X	Х	L	н

logic symbol[†]



[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

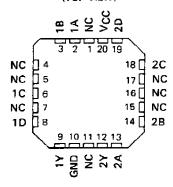
SN5420 . . . J PACKAGE
SN54LS20, SN54S20 . . . J OR W PACKAGE
SN7420 . . . N PACKAGE
SN74LS20, SN74S20 . . . D OR N PACKAGE
(TOP VIEW)

	_	_	1 1		L_	
1A	Ц	1	\cup	14	Ц	Vcc
1B	◁	2		13		2D
NC	□	3		12		2C
1 C	□	4		11		NC
1 D	₫	5		10		2B
1Y	d	6		9		2A
GND	d	7		8		2Y

SN5420 . . . W PACKAGE (TOP VIEW)

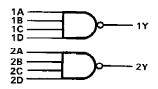
1A	ī	U 14	þ	1 D
1Y	2	13		1C
NC	3	12	Þ	1 B
/cc	4	11	Þ	GND
NC	5	10	Þ	2Y
2A	6	9	Þ	2D
2B	7	8	Þ	2C

SN54L\$20, SN54S20 . . . FK PACKAGE (TOP VIEW)



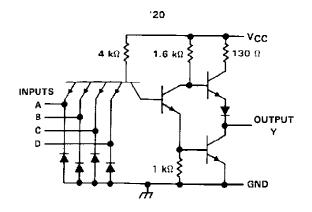
NC - No internal connection

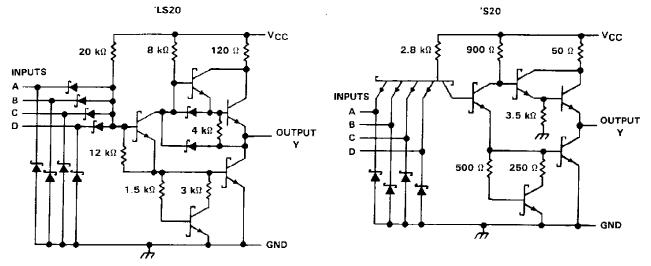
logic diagram



positive logic Y = $\overline{A \cdot B \cdot C \cdot D}$ or Y = \overline{A} + \overline{B} + \overline{C} + \overline{D}

schematics (each gate)





Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)		7 V
Input voltage: '20, 'S20		5.5 V
'LS20		7 V
Operating free-air temperature range:	SN54'	55°C to 125°C
	SN74'	0°C to 70°C
Storage temperature range		65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminals.



recommended operating conditions

			SN5420			SN7420		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	٧
VIH	High-level input voltage	2			2			٧
VIL	Low-level input voltage			0.8			8.0	ν
lон	High-level output current			 0.4			- 0.4	mΑ
loL	Low-level output current			16			16	MΑ
TA	Operating free-air temperature	- 55		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				SN5420			SN742	0	UNIT
PARAMETER		TEST CONDITIONS T			MAX	MIN	TYP‡	MAX	UNIT
VIK	V _{CC} = MIN,	I _j = - 12 mA		-	– 1.5			1.5	٧
Voн	V _{CC} = MIN,	V _{IL} = 0.8 V, I _{OH} = - 0.4 mA	2.4	3.4		2.4	3.4		٧
VoL	VCC = MIN,	V _{IH} = 2 V, l _{OL} = 16 mA		0.2	0.4		0.2	0.4	٧
l _l	V _{CC} - MAX,	V ₁ - 5.5 V			1		_	1	mΑ
ΊΗ	V _{CC} = MAX,	V ₁ = 2.4 V			40			40	μΑ
1 ₁ L	V _{CC} = MAX,	V ₁ = 0.4 V			- 1.6			- 1.6	mA
los§	V _{CC} = MAX		- 20		- 55	_ 18		- 55	mA
іссн	V _{CC} = MAX,	V = 0 V		2	4		2	4	mA
ICCL.	V _{CC} = MAX,	V ₁ = 4.5 V		6	11		6	11	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. ‡ All typical values are at V_{CC} = 5 V, T_{A} = 25°C. § Not more than one output should be shorted at a time.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	IDITIONS	MIN	TYP	мах	UNIT
[†] PLH	A	V	2 400 0	0 45 5		12	22	ns
tРНL	Any	Y	R _L = 400 Ω,	CL = 15 pF		8	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

SN54LS20, SN74LS20 DUAL 4-INPUT POSITIVE-NAND GATES

recommended operating conditions

		SN54LS20			SN74LS20			
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
VCC Supply voltage	4.5	5	5.5	4.75	5	5.25	٧	
V _{IH} High-level input voltage	2			2			٧	
V _{IL} Low-level input voltage			0.7			0.8	V	
IOH High-level output current			- 0.4			- 0.4	mΑ	
IOL Low-level output current			4			8	mΑ	
TA Operating free-air temperature	- 55		125	0		70	°c	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

BA DAMACTED	i	TEST CONDITIONS T			SN54LS	20		SN74LS	20	LINIT
PARAMETER		1257 557/51116115				MAX	MIN	TYP\$	MAX	UNIT
Vik	VCC = MIN,	i = – 18 mA				- 1.5			– 1.5	V
v _{он}	V _{CC} = MIN,	VIL = MAX,	I _{OH} = - 0.4 mA	2.5	3,4		2.7	3.4		v
	V _{CC} = MIN,	V _{IH} = 2 V,	I _{OL} = 4 mA		0.25	0.4			0.4	
VOL	V _{CC} = MIN,	V _{IH} = 2 V,	10L = 8 mA					0.25	0.5	' '
11	V _{CC} = MAX,	V ₁ = 7 V				0.1			0.1	mΑ
liн	V _{CC} = MAX,	V ₁ = 2.7 V				20			20	μА
IIL	V _{CC} = MAX,	V! = 0.4 V				- 0.4			- 0.4	mΑ
IOS §	V _{CC} = MAX		<u> </u>	- 20		- 100	- 20		- 100	mA
Іссн	V _{CC} = MAX,	V = 0 V			0.4	0.8		0.4	8.0	mA
CCL	V _{CC} = MAX,	V ₁ = 4.5 V			1.2	2.2		1.2	2.2	mA

¹ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, VCC = 5 V, TA = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS			TYP	MAX	UNIT
tPLH .	Апу	>	$R_1 = 2 k\Omega$,	C _I = 15 pF		9	15	ns
[‡] PHL	Ally	<u>.</u>	11 - 2 Kaz,	CL - 19 PF		10	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_{\Delta} = 25^{\circ}\text{C}$.

[§] Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

recommended operating conditions

			SN54S20			SN74S20			
		MIN	NOM	MAX	MIN	NOM	MAX	TINU	
V _{CC} Sup	ply voltage	4.5	5	5.5	4.75	5	5.25	V	
V _{IH} Hig	h-level input voltage	2			2	·		٧	
VIL Lov	v-level input voltage			8.0			0.8	V	
OH High	h-level output current			- 1			- 1	mΑ	
IOL LOV	v-level output current			20			20	mΑ	
Тд Оре	rating free-air temperature	- 55		125	0		70	°c	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

0.000.000	TEST CONDITIONS †	SN54S20	SN74S20	UNIT
PARAMETER	TEST CONDITIONS	MIN TYP# MAX	MIN TYP‡ MAX	UNIT
Vik	V _{CC} = MIN, I _f = -18 mA	-1.2	-1.2	٧
∨он	V _{CC} = MIN, V _{IL} = 0.8 V, I _{OH} = 1 mA	2.5 3.4	2.7 3.4	٧
Vol	V _{CC} = MIN, V _{1H} = 2 V, I _{OL} = 20 mA	0.5	0.5	٧
I _I	V _{CC} = MAX, V ₁ = 5.5 V	1	1	mА
IIH	V _{CC} = MAX, V _I = 2.7 V	50	50	μΑ
հը Մ	V _{CC} = MAX, V _I = 0.5 V	-2	2	mΑ
los§	V _{CC} = MAX	-40 -100	-40 -100	mA
¹ ссн	V _{CC} = MAX, V _I = 0 V	5 8	5 8	mA
ICCL	V _{CC} = MAX, V _I = 4.5 V	10 18	10 18	mA

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	MIN	TYP	МАХ	UNIT	
tpLH			R _L = 280 Ω,	C _L = 15 pF		3	4.5	п\$
tPHL	A B C B	Y		OL 10 PI		3	5	ns,
tpLH	A, B, C or D		R _L = 280 Ω,	C _L = 50 pF		4.5		ns
^t PHL						5		ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. ‡ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$. § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.



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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	n MSL Peak Temp ⁽³⁾
JM38510/07006BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/07006BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/07006BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30007B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30007B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30007BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30007BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30007BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30007BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30007SCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30007SCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
JM38510/30007SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30007SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN5420J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN5420J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN54LS20J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54LS20J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54S20J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54S20J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN7420N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7420N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS20D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI



PACKAGE OPTION ADDENDUM

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Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)
SN74LS20J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS20N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS20N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS20N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS20N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS20NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS20NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS20NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS20NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S20D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S20D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S20DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S20DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S20DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S20DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S20DR	OBSOLETE	SOIC	D	0		TBD	Call TI	Call TI
SN74S20DR	OBSOLETE	SOIC	D	0		TBD	Call TI	Call TI
SN74S20N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S20N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S20N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S20N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S20NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S20NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ5420J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ5420J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ5420W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI

PACKAGE OPTION ADDENDUM

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Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SNJ5420W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
SNJ5420WA	OBSOLETE	CFP	WA	14		TBD	Call TI	Call TI
SNJ5420WA	OBSOLETE	CFP	WA	14		TBD	Call TI	Call TI
SNJ54LS20FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS20FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS20J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS20J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS20W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54LS20W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S20FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S20FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S20J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54S20J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54S20W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S20W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS20DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS20NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS20DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74LS20NSR	SO	NS	14	2000	346.0	346.0	33.0

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

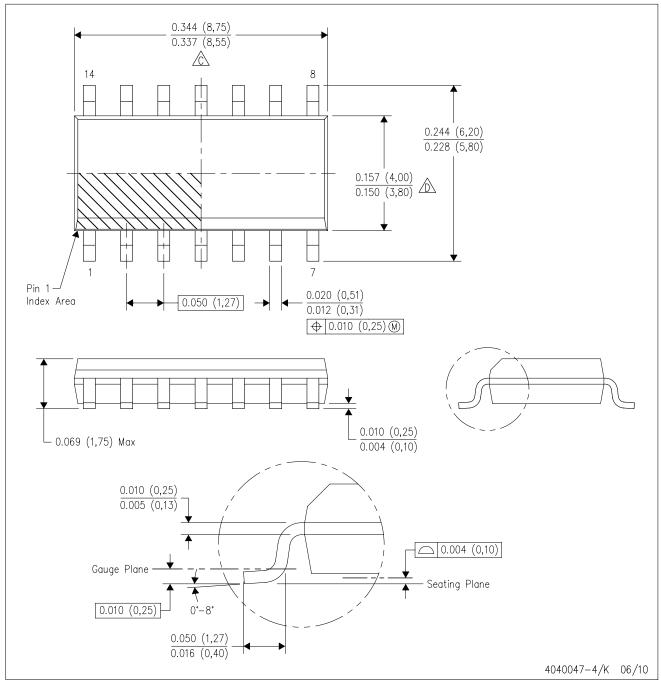


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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